

STN	Skúšanie vplyvu prostredia Časť 2-58: Skúšky Skúška Td Skúšobné metódy spájkovateľnosti, odolnosti proti rozpustnosti pokovovania a odolnosti proti teplu pri spájkovaní povrchovo montovaných častí (SMD) Zmena A1	STN EN 60068-2-58/A1 34 5791
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Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 01/19

STN EN 60068-2-58 z októbra 2015 sa bez tejto zmeny A1 môže používať do 13. 4. 2021.

Obsahuje: EN 60068-2-58:2015/A1:2018, IEC 60068-2-58:2015/AMD1:2017

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EUROPEAN STANDARD

EN 60068-2-58:2015/A1

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2018

ICS 19.040; 31.190

English Version

**Environmental testing - Part 2-58: Tests - Test Td: Test methods
for solderability, resistance to dissolution of metallization and to
soldering heat of surface mounting devices (SMD)
(IEC 60068-2-58:2015/A1:2017)**

Essais d'environnement - Partie 2-58: Essais - Essai Td:
Méthodes d'essai de la soudabilité, résistance de la
métallisation à la dissolution et résistance à la chaleur de
brasage des composants pour montage en surface (CMS)
(IEC 60068-2-58:2015/A1:2017)

Umweltprüfungen - Teil 2-58: Prüfungen - Prüfung Td:
Prüfverfahren für Lötbarkeit, Widerstandsfähigkeit
gegenüber Auflösen der Metallisierung und
Lötwärmebeständigkeit bei oberflächenmontierbaren
Bauelementen (SMD)
(IEC 60068-2-58:2015/A1:2017)

This amendment A1 modifies the European Standard EN 60068-2-58:2015; it was approved by CENELEC on 2017-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this amendment the status of a national standard without any alteration.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN 60068-2-58:2015/A1:2018 (E)**European foreword**

The text of document 91/1445/FDIS, future edition 1 of IEC 60068-2-58:2015/A1, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60068-2-58:2015/A1:2018.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-10-13
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2021-04-13

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The text of the International Standard IEC 60068-2-58:2015/A1:2017 was approved by CENELEC as a European Standard without any modification.



IEC 60068-2-58

Edition 4.0 2017-07

INTERNATIONAL STANDARD



AMENDMENT 1

**Environmental testing –
Part 2-58: Tests – Test Td: Test methods for solderability, resistance to
dissolution of metallization and to soldering heat of surface mounting devices
(SMD)**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

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AMENDMENT 1

Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

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ELECTROTECHNICAL
COMMISSION

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FOREWORD

This amendment has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this amendment is based on the following documents:

FDIS	Report on voting
91/1445/FDIS	91/1451/RVD

Full information on the voting for the approval of this amendment can be found in the report on voting indicated in the above table.

The committee has decided that the contents of this amendment and the base publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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1 Scope

Replace the existing second paragraph of the Scope with the following new paragraph:

This document provides procedures for determining the solderability, resistance to dissolution of metallization and resistance to soldering heat of devices in applications using solder alloys, which are eutectic or near eutectic tin lead (Pb), or lead-free alloys.

koniec náhľadu – text ďalej pokračuje v platenej verzii STN